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個人簡歷

姓名：謝致維

性別：男

出生年月日：民國 70 年 3 月 26 日

籍貫：台灣省台東縣

住址：台東縣池上鄉忠孝路 212 號

學歷：

國立中山大學電機工程學系學士 (88.9 - 93.6)

國立交通大學電子工程研究所碩士 (93.9 - 95.7)

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